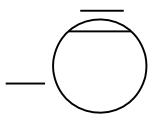
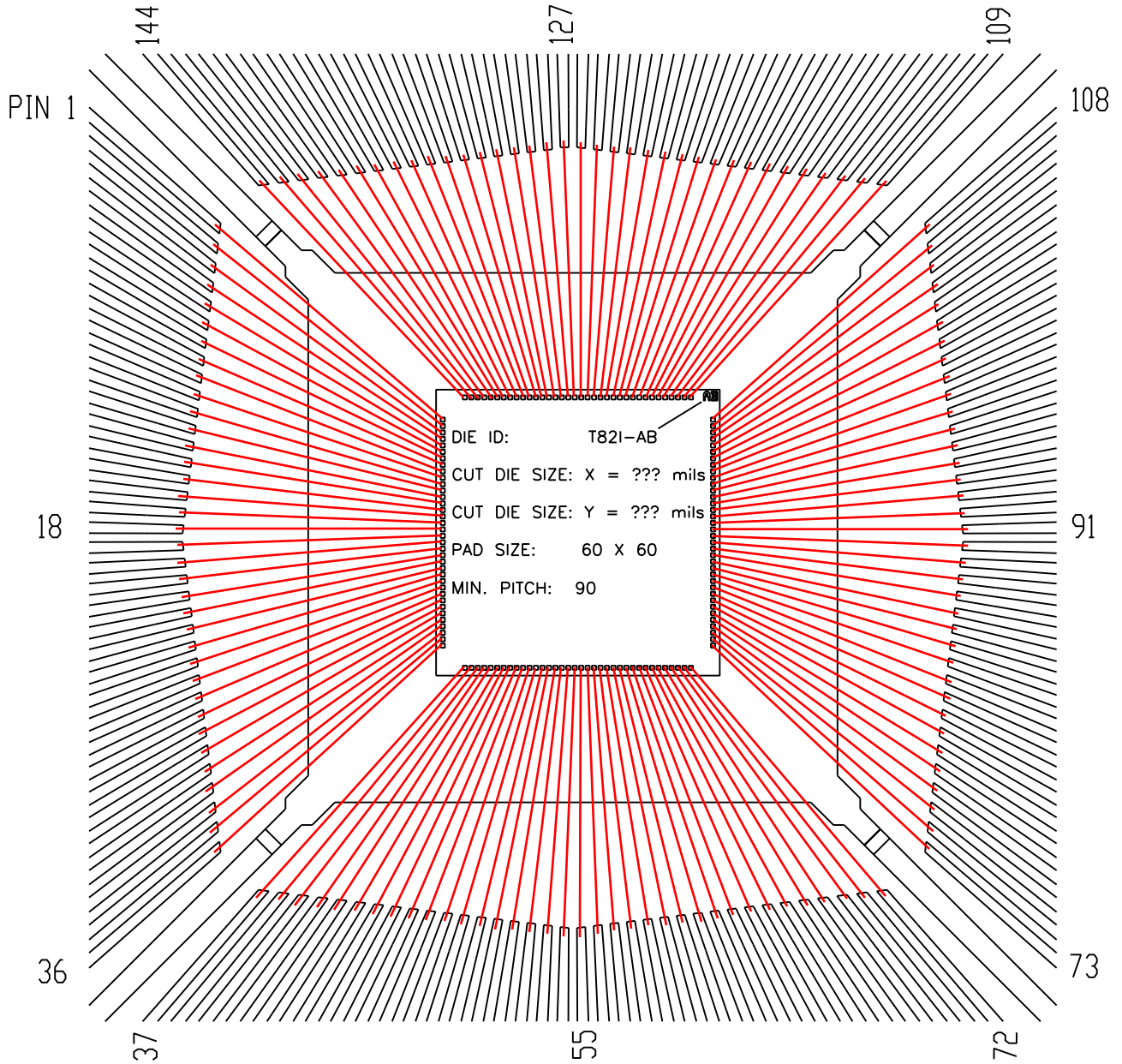


# T82I-AB

## DESIGN #78774



✓ CHECK PIN 1  
DIE ORIENTATION  
WITH RESPECT  
TO WAFER FLAT

LEADFRAME: LF1-D144-204, LF1-D144-205

D/A PAD SIZE: 7.2mm x 7.2mm

SCALE: DO NOT SCALE DRAWING

ECN#	REV.	DESCRIPTION	DATE	DRAWN:	DATE:
8-121	A	NEW RELEASE	05/05/08	LOUIS REZOREKLE	05/09/2000
3-155	B	CHANGED SCALE TO 1X	08/09/00	GEORGE FIDINOTO	05/09/2000
				APPROVED:	DATE
				APPROVED:	DATE
				DWG. NUMBER: QFP-BD-20SQ-144-01	
				ACAD FILENAME: B1442001.DWG	

TITLE:  
BOND SHELL - 20 X 20 X 1.4 TQFP, 144 LD



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